

Title (en)

CIRCUIT CARRIER, (POWER) ELECTRONICS ASSEMBLY AND ELECTRICAL DRIVE DEVICE

Title (de)

SCHALTUNGSTRÄGER, (LEISTUNGS-)ELEKTRONIKANORDNUNG UND ELEKTRISCHE ANTRIEBSVORRICHTUNG

Title (fr)

CARTE DE CIRCUIT IMPRIMÉ, DISPOSITIF ÉLECTRONIQUE (DE PUISSANCE) ET DISPOSITIF D'ENTRAÎNEMENT ÉLECTRONIQUE

Publication

**EP 3881652 A1 20210922 (DE)**

Application

**EP 19813729 A 20191113**

Priority

- DE 102018219574 A 20181115
- EP 2019081131 W 20191113

Abstract (en)

[origin: WO2020099464A1] The present invention discloses a circuit carrier (20) for establishing a mechanical and electrical connection for at least one (power) electronic component (500), comprising: - a support plate (100) which has at least one through-hole (200); - at least one electrically and thermally conductive insertion element (300) which is arranged in the through-hole (200) and has a first contact surface (301) for establishing electrical and thermal connections to the component (500) and a second contact surface (302), facing away from the first contact surface (301), for establishing thermal connections to a cooling body (600); - wherein the insertion element (300) also forms a feedthrough (210) and has a lateral contact face (303) which abuts the feedthrough (210) and is designed to establish an electrical and thermal connection to an electrical connection element (710).

IPC 8 full level

**H05K 1/02** (2006.01); **H02K 11/33** (2016.01); **H02M 7/00** (2006.01); **H05K 1/18** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP US)

**B60L 53/20** (2019.01 - US); **B60R 16/0231** (2013.01 - US); **H02K 9/223** (2021.01 - EP US); **H02K 9/227** (2021.01 - EP US); **H02K 11/33** (2016.01 - EP US); **H02M 7/003** (2013.01 - EP); **H05K 1/0265** (2013.01 - EP); **H05K 1/18** (2013.01 - EP); **H05K 1/181** (2013.01 - EP); **H05K 3/0061** (2013.01 - EP); **H02K 2211/03** (2013.01 - US); **H02M 1/327** (2021.05 - EP); **H05K 1/0204** (2013.01 - EP); **H05K 2201/066** (2013.01 - EP); **H05K 2201/1009** (2013.01 - EP); **H05K 2201/10166** (2013.01 - EP); **H05K 2201/10272** (2013.01 - EP); **H05K 2201/10303** (2013.01 - EP); **H05K 2201/10416** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP); **Y02T 10/70** (2013.01 - EP); **Y02T 10/7072** (2013.01 - EP); **Y02T 90/14** (2013.01 - EP)

Citation (search report)

See references of WO 2020099464A1

Designated contracting state (EPC)

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BA ME

DOCDB simple family (publication)

**DE 102018219574 A1 20200520**; CN 113039870 A 20210625; EP 3881652 A1 20210922; US 2021273533 A1 20210902; WO 2020099464 A1 20200522

DOCDB simple family (application)

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